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**GEOMETRIC
SOLUTIONS**

Simcenter 3D Space Systems Thermal

Space orbital thermal analysis

Benefits

- Predict thermal performance for orbiting vehicles accurately and quickly
- Reduce costly physical prototypes by using thermal simulation to understand product performance
- Increase collaboration and team productivity with a thermal analysis solution that is easily integrated with your design and engineering process
- Leverage all the capabilities of the Simcenter 3D integrated environment to make quick design changes and provide rapid feedback on thermal performance
- Maximize process efficiency with a highly automated solution that requires no additional input files and carries out analysis in a single pass

Summary

Simcenter™ 3D Space Systems Thermal software is the space industry vertical application that provides a comprehensive set of tools to conduct orbital thermal analyses within the Simcenter 3D environment. Simcenter 3D Space Systems Thermal helps resolve thermal engineering challenges early in the design process and is a valuable tool for predicting and understanding thermal physics for space-bound, orbiting and interplanetary vehicles.

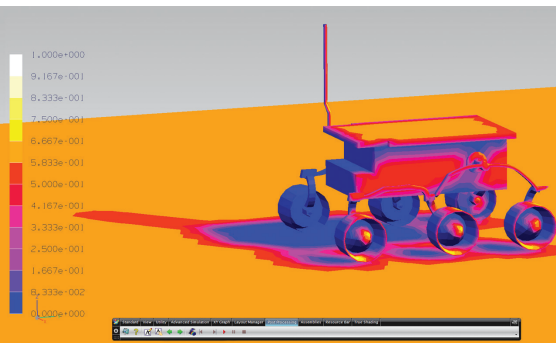
Simcenter 3D Space Systems Thermal continues Siemens' long heritage in thermal simulation and leverages the same technology that underpinned the I-deas™ TMG solution. Simcenter 3D Space Systems Thermal is ideal for orbital vehicle applications with complex 3D design geometry. Users can easily employ Simcenter 3D Space Systems Thermal to build small thermal models for conceptual studies all the way to detailed geometry-based models when high-fidelity analysis is required.

The Simcenter 3D Space Systems Thermal module enables you to effectively use simulation to provide design

guidance early in the design cycle instead of just during design verification. Modeling of complex and/or large 3D CAD assemblies is made easy with the prerequisite Simcenter 3D Engineering Desktop capabilities. No additional input files or geometry conversions are needed to build your thermal analysis models. Simcenter 3D is an open system with multi-CAD support which makes it easier for you to work with supplier- or contractor-provided geometry that originates from another CAD system. Simcenter 3D provides a distributed model approach to assembly analysis whereby the assembly FEM model does not contain the component FEM models, but instead holds pointers to these models. Assembly FEM enables a more efficient process for building large models comprised of multiple components. Synchronous technology enables users to modify geometry by easily moving or deleting individual faces or features such as bosses or ribs. Synchronous technology empowers analysts to make simple changes to geometry to support what-if analyses, thereby accelerating design-analysis iterations. Furthermore, this technology works with native and imported geometry, both with or without history.

Simcenter 3D Space Systems Thermal also has embedded interfaces with other legacy and commercial software tools used for radiation and thermal analysis in the space systems industry.

Simcenter 3D Space Systems Thermal



Main Simcenter 3D Space Systems Thermal features

Specific thermal analysis capabilities for the space industry include:

- Orbital heating modeler for all planets of the solar system
- Orbit Visualizer window to display the aim, align, satellite-sun and satellite-planet vectors
- Powerful and fast view factor calculations (including parallel computing for large Space Systems Thermal models)
- Transient view factor recalculations for the case of articulating geometries, such as for sun-tracking solar panels or directional antennas
- Multi-layer shell formulation for modeling MLI, composite panels and TPS applications
- Direct interfaces to other radiation and thermal analysis tools for space systems:

| | | |
|--------|--------|----------|
| SINDA | TSS | TRASYS |
| ESATAN | ESARAD | Thermica |

Core solver capabilities

- Steady-state and transient analysis of linear and nonlinear problems
- Preconditioned bi-conjugate gradient solver technology
- Fully coupled conduction, radiation and convection heat transfer simulation
- Axisymmetric modeling
- 1D duct and hydraulic network elements
- Motion modeling (translational motion and rotational joints)

Conduction heat transfer

- Ability to handle very large thermal models
- Temperature-dependent conductivity and specific heat
- Orthotropic conductivity

Radiation heat transfer

- Constant, temperature-dependent and wavelength-dependent emissivity
- Multiple radiation enclosures
- Diffuse view factor calculations with shadowing
- Hemicube-based view factor calculations using graphics hardware
- Ray-traced view factors to account for specular effects

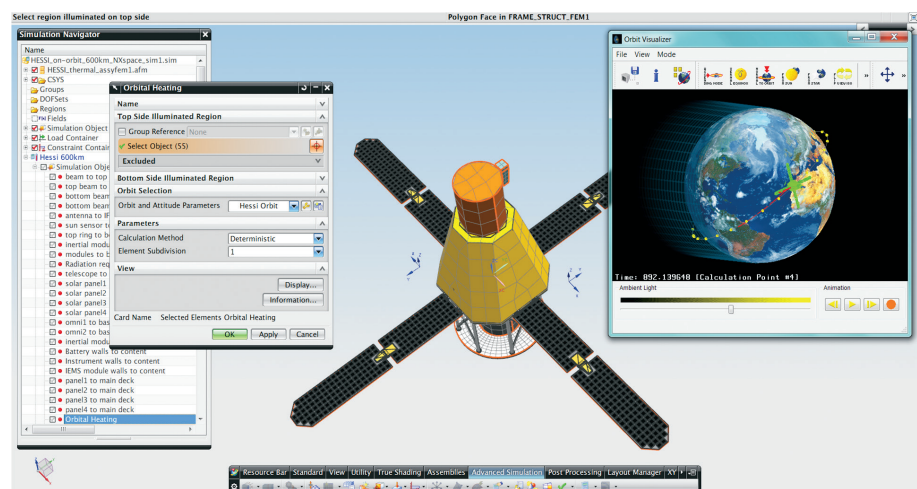
- Monte Carlo and deterministic ray-tracing methods
- Adaptive scheme for view factor sum optimization
- Radiation patch generation to condense large element-based radiation models
- Defined radiative heat sources (collimated or diffuse, time and spatially varying fluxes)

Convection heat transfer

- Constant, time- and temperature-dependent heat transfer coefficients
- Correlation-based free and forced convection to ambient for inclined plates, cylinders and spheres
- Coupling to 1D duct networks

Thermal coupling technology for modeling thermal contacts within assemblies

- Thermally connect disjoint and dissimilar mesh faces and edges
- Constant, time- and temperature-dependent and spatially varying heat transfer coefficients
- Surface-to-surface, edge-to-edge or edge-to-surface contact modeling between parts
- Radiative exchange between disjoint part faces and faces within a single part



- Interface modeling between connected parts
- Convective exchange correlations between faces: parallel plates, concentric spheres or cylinders
- Advanced thermal connections: join, one-way heat transfer (advection), user-defined heat transfer

Optical and other advanced material properties

- Advanced optical properties including temperature and angle dependence (BRDF)
- Transmissivity, specular reflectivity, refraction, extinction through solid media
- Electrical resistivity
- Latent heat of fusion at phase change temperature
- Ablation and charring of materials

Temperature boundary conditions and applied heat loads

- Time and spatially varying temperature boundary conditions
- Heat loads, heat flux and heat generation: variable in time and space
- Electrical Joule heating
- Free Molecular Heating

Initial conditions

- Spatially varying initial temperatures for both steady-state and transient analysis
- Initial temperatures from previous solution results and from file

Thermal control models

- Thermostats, active heater controllers, PID
- Peltier cooler
- User-defined control system logic

Solver solution attributes

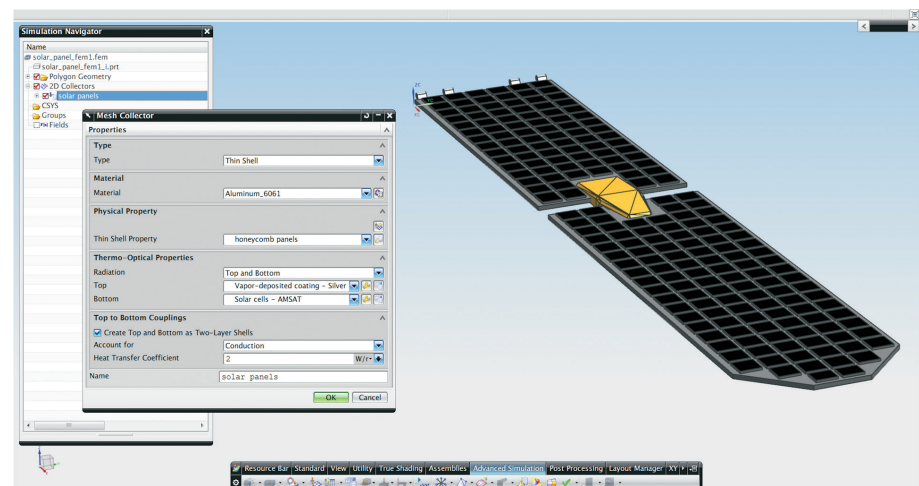
- Restart conditions
- Orbit periodic convergence criteria
- Direct access to solver parameters
- Solver convergence criteria and relaxation factors
- Solver monitor with solution convergence and attributes
- Intermediate results display and recovery directly from solver progress monitor
- Open architecture (user subroutines)
- Support to include external input files
- Thermal solver multithreading

Parallel processing

- Up to eight processes per analysis on a single machine
- Unlimited processes across multiple machines, including support for clusters, with Simcenter 3D Thermal/Flow DMP add-on

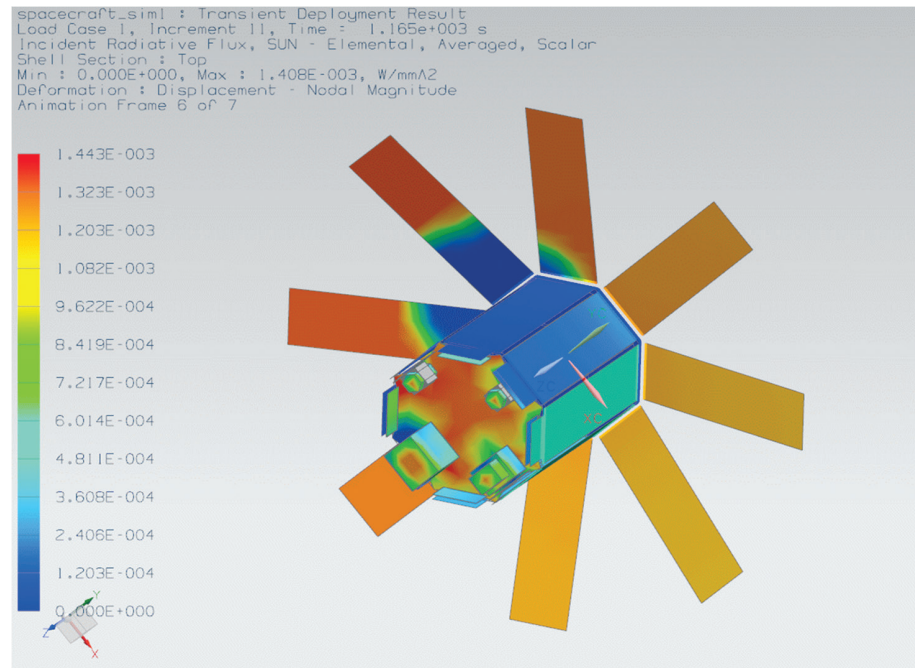
Other features

- Results reports
- Summary of results in HTML and comma separated values (.csv) format compatible with Excel
- Heat flow calculation between groups
- Heat maps
- Complete or partial deactivation of selected elements from conduction and/or radiation calculations; useful for what-if analysis
- Override material properties for what-if and EOL/BOL analysis
- Temperature mapping to Nastran™ FE models and external solvers
- Import and export of the STEP-TAS radiation model
- Merge elements for reduced model preparation
- Geometry optimization supporting flexible design objectives and variables



Results postprocessing

- Temperatures
- Temperature gradients
- Total loads and fluxes
- Conductive fluxes
- Convective fluxes
- Convection coefficients
- Residuals
- Heat maps
- Joule data
- Phase change quality
- RC products
- Apparent temperatures
- Radiance
- Net radiative, radiosity and irradiance fluxes
- Orbital and radiative source fluxes and view factors
- View factors sums



Industry applications

Typical space systems thermal analysis applications include:

- Transient and steady-state orbital heating simulation
- MLI and TPS design, modeling and performance analysis
- Re-entry vehicle aero-heating and thermal ablation modeling
- Thermal subsystems optimization
- Interplanetary spacecraft thermal design and analysis
- Material coating selection
- Thermal shock transient simulations
- Orbital maneuvering transient thermal simulations
- Thermal management systems design and analysis
- Space test-bed experimental apparatus thermo-fluid analysis
- Space station and future space modules HVAC
- Gray Body View Factors (GBVF) to space

Supported hardware/OS

Simcenter 3D Space Systems Thermal is an add-on to Simcenter 3D Engineering Desktop in the Simcenter 3D suite of applications. It requires a Simcenter 3D Engineering Desktop license as a prerequisite. All standard Simcenter 3D hardware/OS platforms are supported (including Windows, Linux and selected 64-bit platforms). Contact Siemens PLM Software for any other specific hardware/OS support requests.

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